

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) An optical waveguide module comprising:

an optical waveguide circuit chip having an optical waveguide forming area formed on a substrate; and

a package for supporting and storing the optical waveguide circuit chip in at least a peripheral portion of an edge portion; ,wherein

an elastic member for impact relaxation of said optical waveguide circuit chip is arranged in at least one portion of the vicinity of the edge portion of said optical waveguide circuit chip, and

the elastic member is formed in a U-like shape in section in which the optical waveguide circuit chip is nipped from its front and rear sides.

2. (Canceled)

3. (Original) An optical waveguide module according to claim 1, wherein the elastic member is arranged in the vicinity of at least one set of opposite corners of the optical waveguide circuit chip.

4. (Original)An optical waveguide module according to claim 1, wherein the optical waveguide circuit chip has a quadrilateral planar shape, and

the elastic member is arranged in the vicinity of each of three or more corner portions of said optical waveguide circuit chip.

5. (Original)An optical waveguide module according to claim 1, wherein the elastic member for impact relaxation of said optical waveguide circuit chip is arranged on at least one of front and rear sides of the optical waveguide circuit chip.

6. (Original)An optical waveguide module according to claim 1, wherein a fitting concave portion for fitting the elastic member thereinto is arranged in the package.

7. (Original)An optical waveguide module according to claim 1, wherein a clearance is formed in at least one of a portion between the optical waveguide circuit chip and the elastic member, and a portion between the elastic member and the package.

8. (Original)An optical waveguide module according to claim 1, wherein the elastic member is formed by fluoro-elastomer.

9. (Original)An optical waveguide module according to claim 1, wherein the optical waveguide forming area of the optical waveguide chip has:

- at least one optical input waveguide;

- a first slab waveguide connected to an output side of the optical input waveguide;

- an arrayed waveguide connected to an output side of the first slab waveguide and constructed by plural channel waveguides having lengths different from each other by set amounts and arranged side by side;

- a second slab waveguide connected to an output side of the arrayed waveguide; and

- one or more optical output waveguides connected to an output side of the second slab waveguide.

10. (Original)An optical waveguide module according to claim 1, wherein the optical waveguide forming area of the optical waveguide circuit chip has:

- at least one optical input waveguide;

- a first slab waveguide connected to an output side of the optical input waveguide;

- an arrayed waveguide connected to an output side of the first slab waveguide and constructed by plural channel waveguides having lengths different from each other by set amounts and arranged side by side;

- a second slab waveguide connected to an output side of the arrayed waveguide; and

- one or more optical output waveguides connected to an output side of the second slab waveguide;

wherein separating slab waveguides are formed by separating at least one of said first and second slab waveguides on a face crossing a path of light passing through the slab waveguides; and

a slide moving member for sliding and moving at least one side of the separating slab waveguide along said separating face in accordance with temperature is arranged.